

Welcome to

MWX PCB

Your Reliable Partner for Prototypes & Small Series

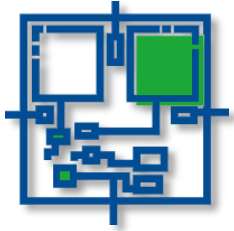
Capability Profile

March 2026

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» Who we are



**Focus on PCB R&D and
manufacturing**

13 years



**China Printed Circuits
Association**

**Quality
Manufacturer**



**Small and medium batch,
high-end prototype MFG**

**Leading
company**



Quick global delivery

**Superior
company**



ISO 9001



ISO 14001



IATF 16949



ISO 45001

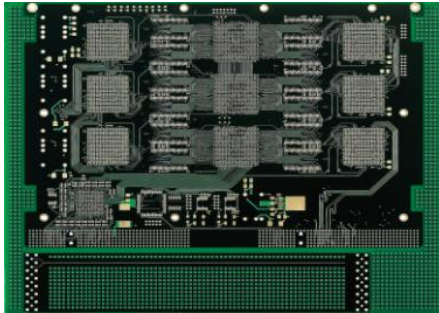


ISO 13485

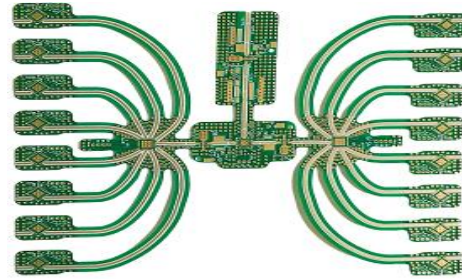


**RoHS
REACH**

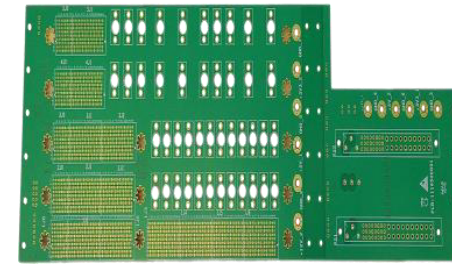
» Our products and services



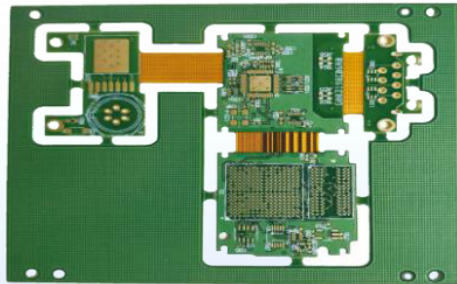
HDI



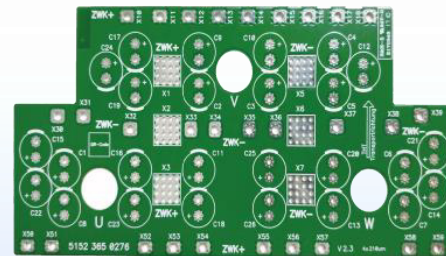
High Frequency



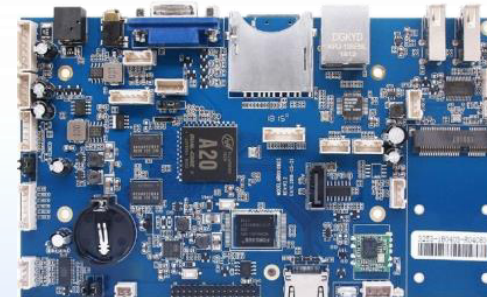
High-speed



Rigid-flex



Heavy copper



PCBA

PCB processing: 1-50 layers rigid board, HDI, rigid-flex, high frequency, high speed, heavy copper, etc.

» Major Production Equipment



Online LDI



Drilling



PTH



VCP



Laminator



ENIG

» Auto Online Inspection Equipment



**Online Board Tk
Measurement 100%**



Online Hole Check: 100%



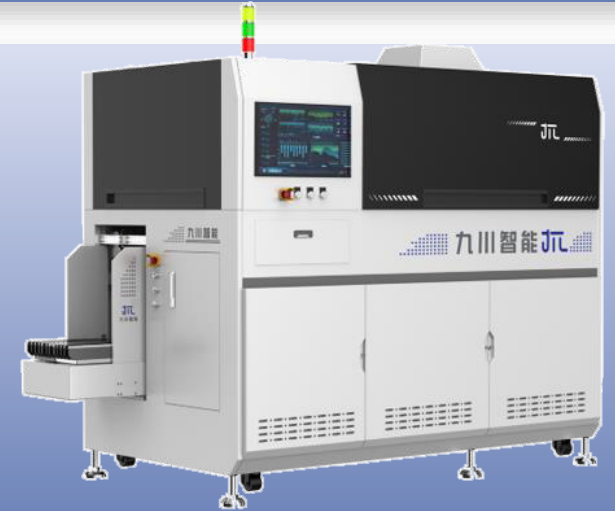
Online AOI: 100% Inspect



**Hole-wall Copper
Measurement 100%**



E-test: 100%

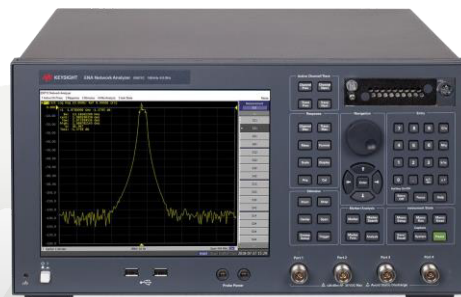


AVI: 100% Inspect

» Major Inspection Equipment



Inductance Tester



Impedance Tester



Image Dimension Measurement



Metallographic microscope



Finished Hole Inspection Machine



Hole AOI / Express

» Major Inspection Equipment



Saltfog Chamber



RoSH 2.0 Tester



Ionic Contamination Tester



Hi-Speed Full Dimension Measurement



Environment Chamber



SEM & EDS

» Delivery date

Shenzhen

Jiangxi

Types	≤1m ² / lot		≤1m ² / lot		≤15m ² / lot		
	Working days	Normal leadtime	Quickest leadtime	Normal leadtime	Quickest leadtime	Normal leadtime	Quickest leadtime
2L		5	1	4	2	7	4
4L		5	2	5	3	8	5
6L		6	3	5	3	9	6
8L		7	3	6	4	10	7
10L		9	4	7	5	12	8
12L		9	4	8	5	13	8
14L		10	5	9	6	14	10
16L		11	5	11	7	15	11
18L		12	6	11	7	15	11
20L		13	7	13	8	17	13
22L		14	8	13	8	17	13
24L		15	9	15	9	19	14
26L		16	10	16	10	20	15
28L		17	11				
30L		19	12				
32L		21	13				
34L		23	14				
36L		25	15				
38L		27	16				
40L		29	17				
> 40L		It depends					

Remark:

- 1.The above leadtime is calculated as 6 working days per week, excluding public holidays;
- 2.The above leadtime excludes EQ confirmation time and transportation time;
- 3.The above leadtime is based on the common parameters, if there is a special process, it needs to be appropriately extended (such as heavy copper, peelable soldermask, HDI, etc.);
- 4.For quick-turn service, please contact our staff.

» Process Capability

Items	Processing capability (Shenzhen Plant)	Processing capability (Jiangxi Plant)
Layers (max)	50	26
Board thickness range	0.20 mm -- 5.6 mm	0.4 mm -- 3.00 mm
Outlayer line width / line distance (min)	3.0/3.0 mil	4/4 mil
Outlayer copper thickness (max)	30 OZ	4 OZ
Inlayer copper thickness (max)	15 OZ	4 OZ
Aspect ratio (max)	20:1	10:1
Board thickness tolerance	t ≥ 0.8mm, ± 10%; t < 0.8mm, ± 0.08mm	
Finished hole size dia(mechanical drill)	0.15mm -- 6.50mm	
Hole position tolerances (mechanical drill)	± 0.05mm	
Outline tolerance	± 0.05mm (±2 mil)	
Soldermask dam width(min)	0.075mm (green) / 0.125mm (other color)	
Impedance tolerance	< 50Ω: ±5Ω, ≥50Ω: ±10%	
Surface treatment	HAL LF, Immersion gold, ENIG, Immersion tin, Immersion silver, OSP, hard gold finger, carbon ink, peelable soldermask, etc.	
Special process	POFV, buried/blind vias, back-drilling, control-depth milling, hybrid materials PCB, counterbore, copper via plugging, etc.	

S: Sample

Shenzhen plant

Jiangxi plant

Product	Structure /parameters	2025	2026*	2027*	2025	2026*	2027*
Multilayer	Line width (min)	3.0/3.0 (S)	2.5/2.5 (S)	2.5/2.5 (S)	4.0/4.0	3.5/3.5 (S)	3.0/3.0 (S)
	Line width tolerance	±0.8mil	±0.5mil (S)	±0.5mil (S)	±1mil	±0.8mil(S)	±0.8mil (S)
	Layers (max)	50 (S)	56 (S)	60 (S)	26	28	30
	Aspect ratio	20:1(4.0/0.25) (S)	22:1(5.5/0.25) (S)	24:1(6.0/0.2) (S)	8:1 (1.6/0.2)	9:1 (1.8/0.2)	10:1(2.0/0.2)
Heavy copper	Outlayer copper thickness (max)	30 OZ	30 OZ	30 OZ	4 OZ	4 OZ	4 OZ
	Inner layer copper thickness (max)	15 OZ	15 OZ	15 OZ	4 OZ	4 OZ	4 OZ
Buried blind via	Steps (number of pressing)	3 (S)	3 (S)	4 (S)	2 (S)	2	2
	Dimple PoFV(um)	≤75	≤50	≤25	≤75	≤50	≤25
HDI (S)	Blind via aspect ratio	0.8:1	1:1	1:1	0.8:1	0.8:1	0.8:1
	Via plugging aspect ratio	0.8:1	0.8:1	0.8:1	0.8:1	0.8:1	0.8:1
	Steps	5	6 (S), Any-layer (S)	6 (S), Any-layer (S)	1	2	3
Rigid-flex(S)	Flex board layers	12	16	18	/	/	/
	Structure	Books, pontoons, flying tails	Books, pontoons, flying tails	Books, pontoons, flying tails	/	/	/

» Main material



tuc

Conventional
FR4

S1141/S1000H/S1000-2M;
IT-158TC/IT-180ATC; KB-6160/KB-6165G/KB-6167F
TU-768/TU-865; ISOLA 370HR



KB

Halogen
free

S1150G; TU-747T/TU-865

Panasonic

isola®

High
frequency

S7135D/S7136
RO3003™/RO4003C™/RO4350B™/RO4730G3/RO5880
AGC TLY-5; ROGERS AD255CTM; F4B

ITEQ



High speed

TU-872 SLK/TU-883/TU-933+; M-4/M-6/M-7;
IT-968/ IT988G; ISOLA FR408/I-Speed®/Tachyon-100G

High thermal
conductivity
/ High CTI

ST115G/S1600

TACONIC



Flexible
material

PI: SF202/SF305(Adhesive); AP-85 Series/AP-91 Series;
Panasonic R-F775; Coverlay: SF305C

1.6T optical module

Layer

14 layers

Material

IT988GES

Via to trace
gap

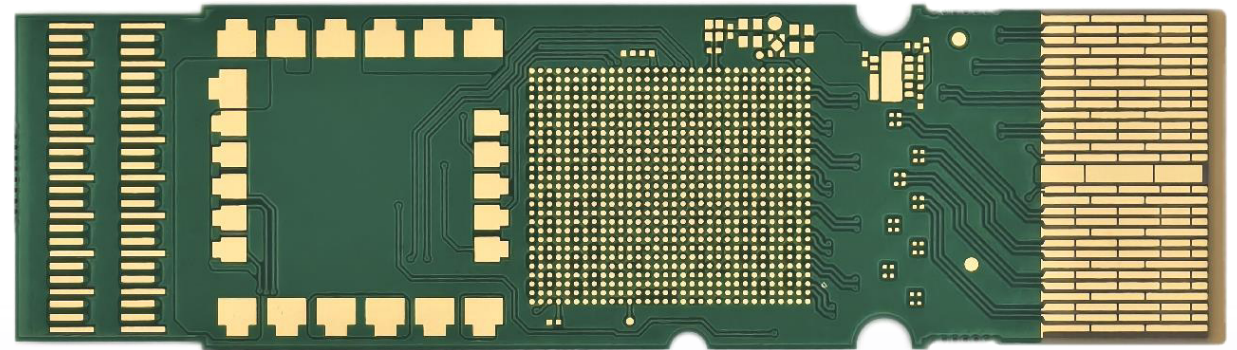
7.1mil

Line width/
Line space

4/4mil

Impedance

±5%



Special Processes

- 4-steps HDI
- Resin Plugged Vias
- Controlled Depth Drilling
- Stepped/Staggered Gold Fingers + ENEPIG (Electroless Nickel)
- Via-in-Pad

Filter

Layer

6 layers

Material

S7136H+TU862HF

Line width/
Line space

10/4mil

Via to trace
gap

8mil

Minimum via
size

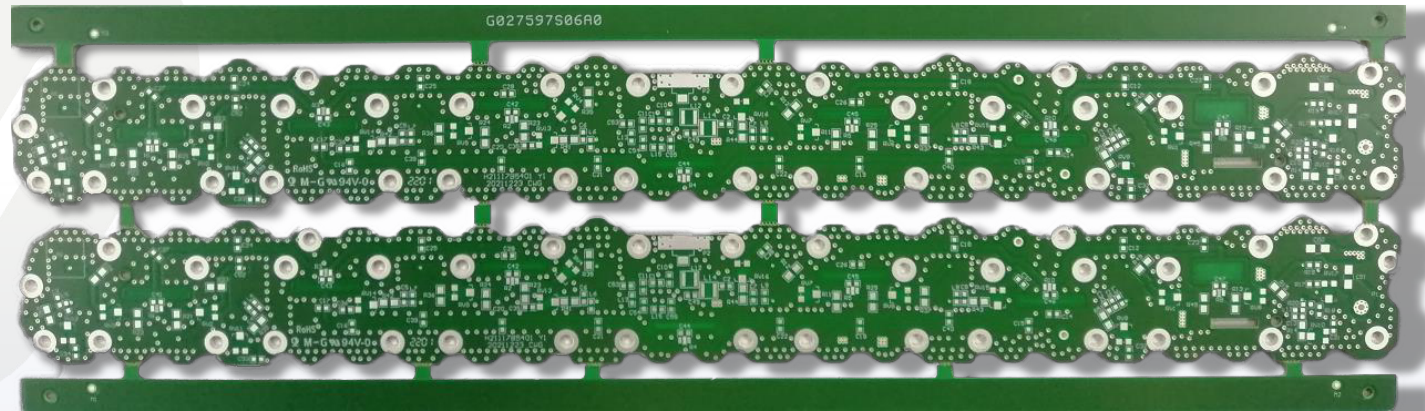
0.3mm

Aspect ratio

6:1

Surface
treatment

Immersion silver



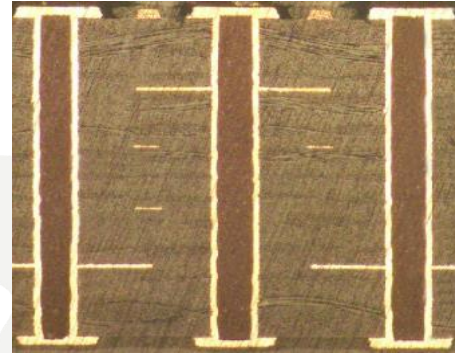
» Product display - high multi-layer



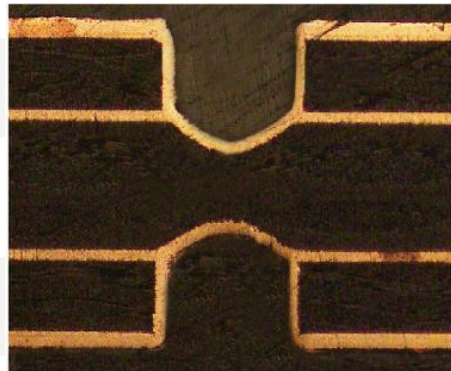
High aspect ratio



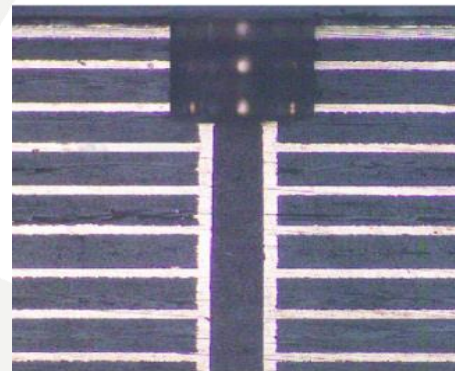
Buried blind via



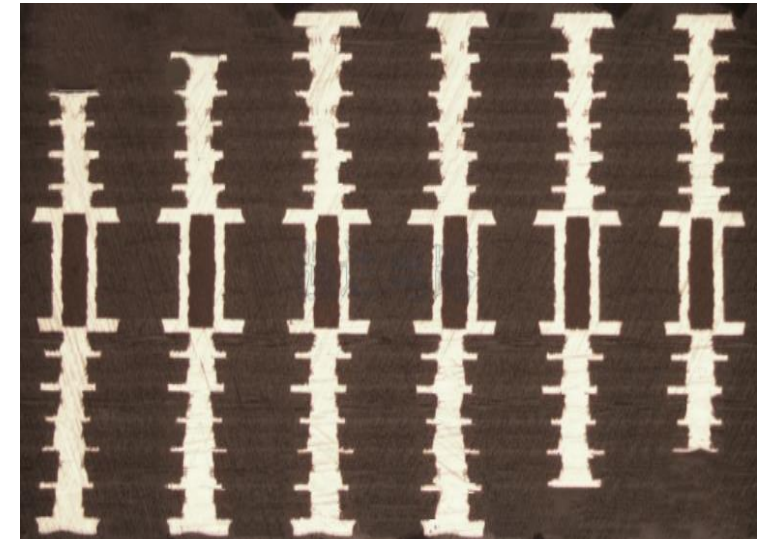
POFV



Mechanical depth blind via



Backdrill



HDI

» Why customers choose MWX

► **Positioning:** Near 13 years of continuous focus on high-end samples, small and medium batch fields.

► **Features:** *Fast delivery, quality stability.*

► **Products:** 1-50 layers of samples, small and medium batches, all kinds of special technology, special materials (high frequency and high speed), HDI, rigid and flexible combination, etc.

► **Services:** Good at providing differentiated and flexible services.

JUST IN TIME





THANKS

Partnering with innovators to accelerate your breakthroughs

Jul. 2025
